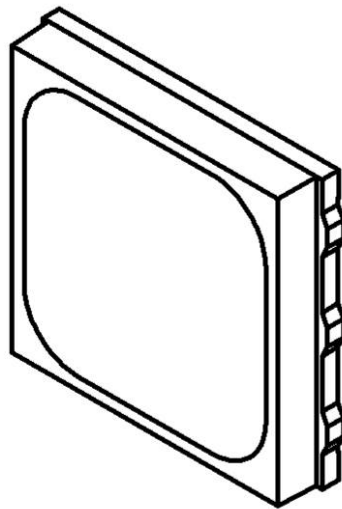


BBSMD5050-BB2-60-003



BBSMD5050-BB2-60-003

Broad Band LED



Features

- Chip size: $1.1 \times 1.1\text{mm}$
- Number of Chips: 1pc
- Excitation Wavelength: 450nm
- Optical efficiency (typ.) : Typ.170mW
- Viewing half angle: 55°
- Package: Resin
- Lens: Phosphor-mixed Silicone Resin

Applications

Maximum Ratings (Tc=25°C)

Parameter	Symbol	Values	Unit
Power Dissipation	P _D	1800	mW
Forward Current	I _F	500	mA
Pulse Forward Current	I _{FP}	1000	mA
Reverse Voltage	V _R	5	V
Junction Temperature	T _j	115	°C
Operating Temperature	T _{opr}	-40~100	°C
Storage Temperature	T _{stg}	-40~100	°C
Thermal Resistance	R _{thjs}	10	°C/W

※Pulse Forward Current Condition : Duty 1% and Pulse Width=1ms.

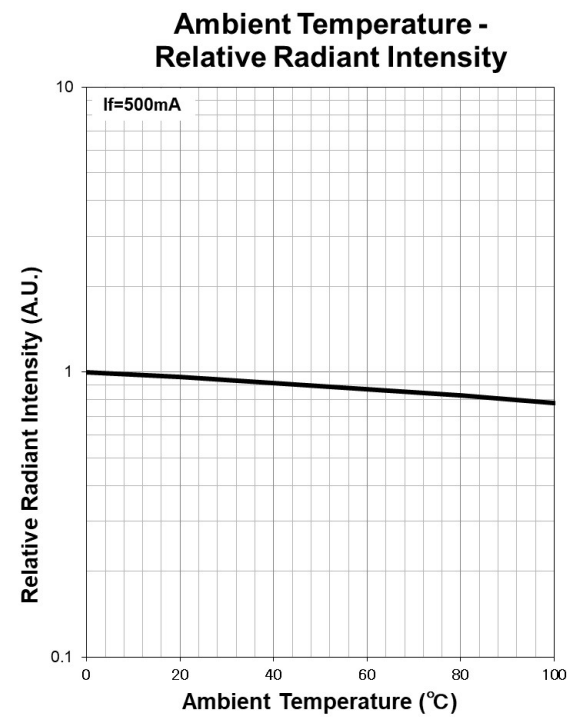
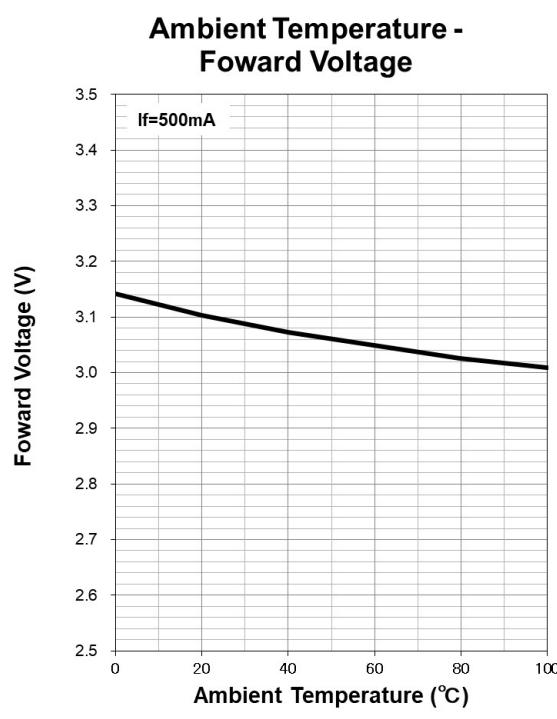
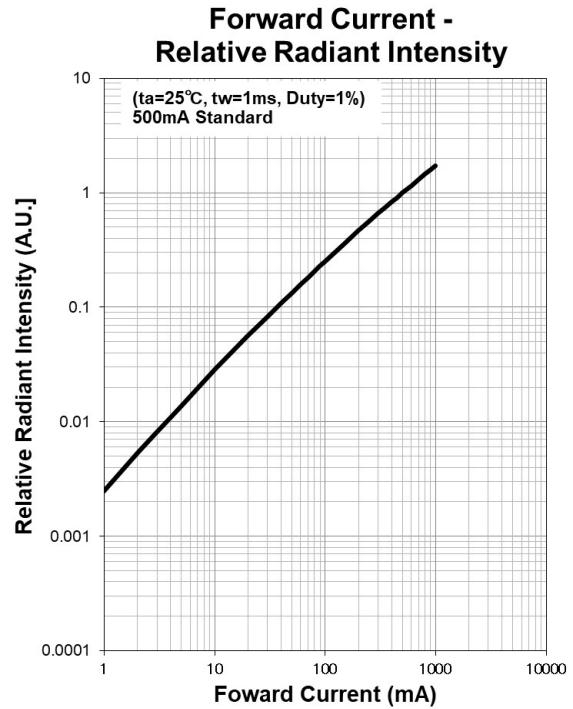
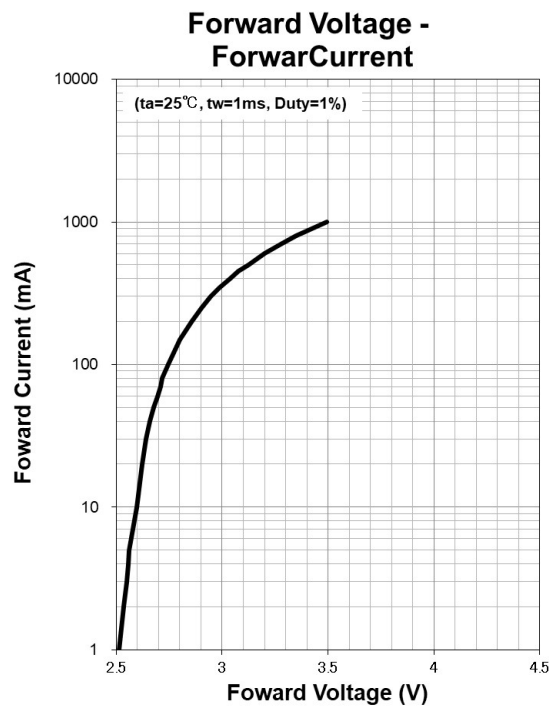
※Soldering condition : Soldering condition must be completed with 5 seconds at below 260°C

Optical and Electrical Characteristics (Tc=25°C)

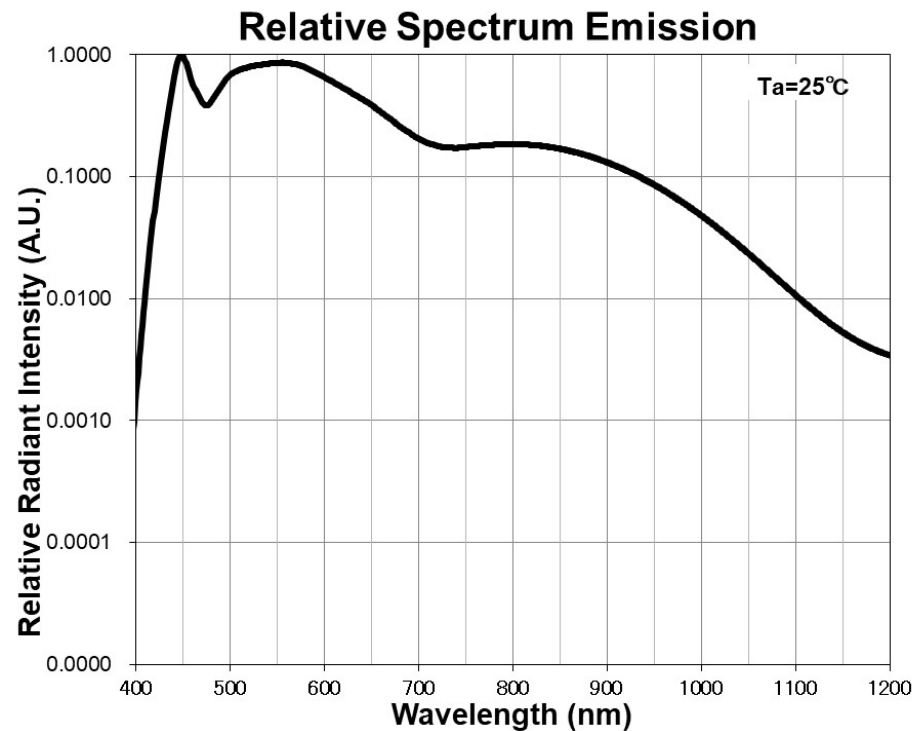
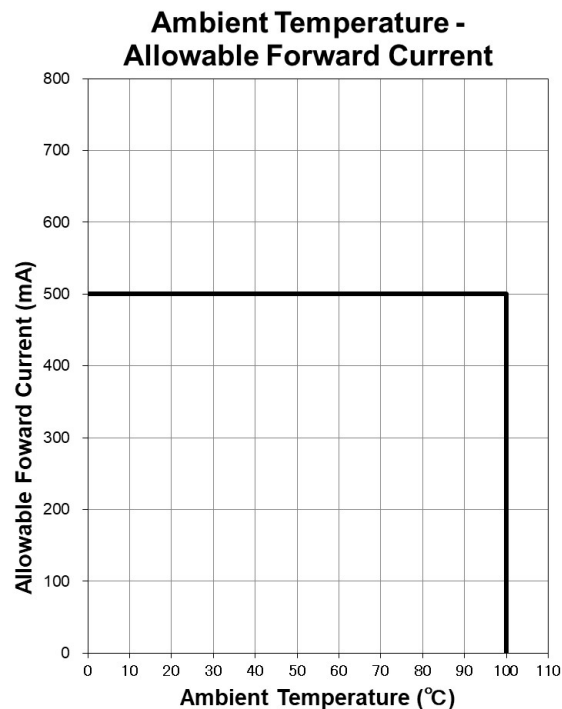
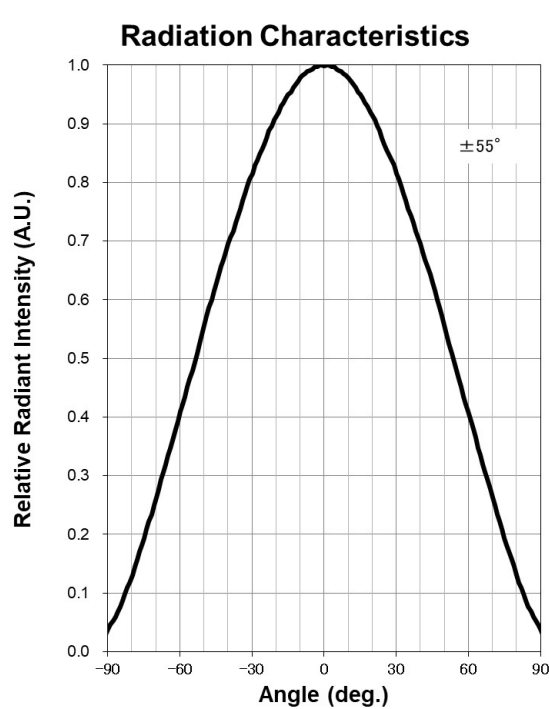
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage	V _F		3.1	3.6	V	I _F =500mA
	V _{FP}		3.5		V	I _{FP} =1000mA
Radiated Power	P _O		170		mW	I _F =500mA
			317		mW	I _{FP} =1000mA
Total luminous flux	Im		70		lm	I _F =500mA
Correlated color temperature	T _c		5430		K	I _F =500mA
Excitation wavelength	λ		450		nm	I _F =500mA
Viewing Half Angle	θ 1/2		55		deg	I _F =100mA

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Typical Characteristic Curves

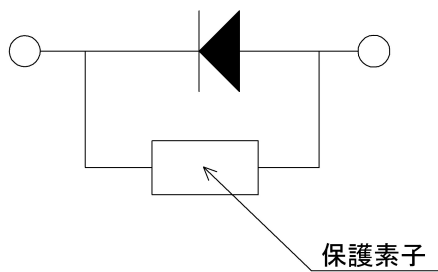
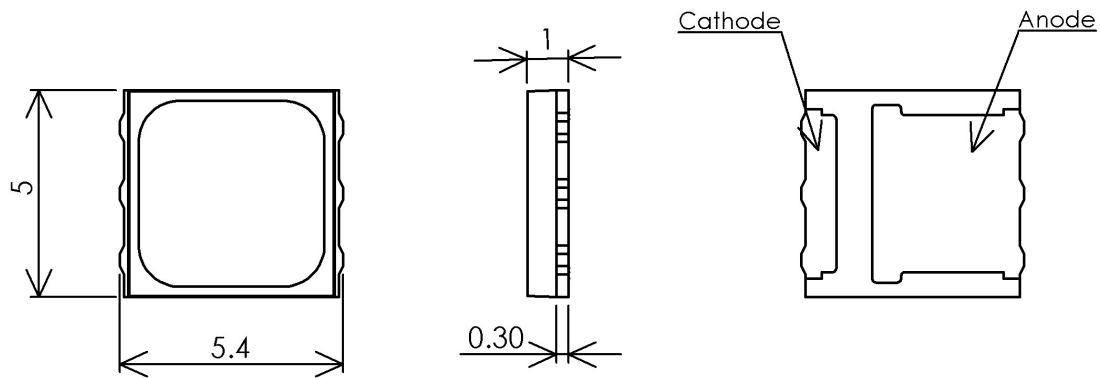


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Outline and Internal Circuit



Oct. 2019